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## 6V, 1A, 1.5MHz, CMCOT Synchronous Step-Down Converter

### General Description

The RT5710B is a simple, easy-to-use, 1A synchronous step-down DC-DC converter with an input supply voltage range of 2.5V to 6V. The device build-in an accurate 0.6V reference voltage and integrates low  $R_{DS(ON)}$  power MOSFETs to achieve high efficiency in a WDFN-6L 2x2 package.

The RT5710B adopts Current Mode Constant On-Time (CMCOT) control architecture to provide an ultrafast transient response with few external components and to operate in nearly constant switching frequency over the line, load, and output voltage range. The RT5710B operates in Forced PWM that helps meet tight voltage regulation accuracy requirements.

The RT5710B senses Low-Side FETs current for a robust over-current protection. It features cycle-by-cycle current limit protection and prevent the device from the catastrophic damage in output short circuit, over current or inductor saturation. An Internally soft-start function prevents inrush current during start-up. The device also includes input under-voltage lockout, output under-voltage protection, and over-temperature protection (thermal shutdown) to provide safe and smooth operation in all operating conditions. The RT5710B is offered in a WDFN-6L 2x2 package.

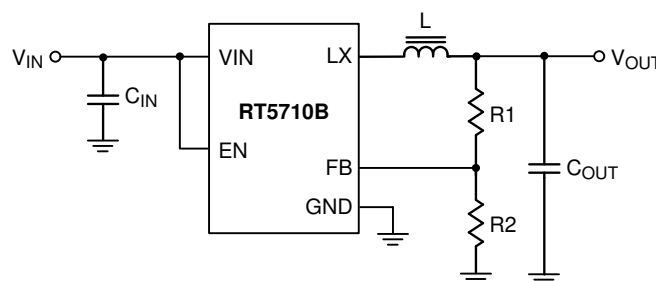
### Features

- **1A Converter With Built-In 160mΩ/110mΩ Low  $R_{DS(ON)}$  Power FETs**
- **Input Supply Voltage Range : 2.5V to 6V**
- **Output Voltage Range : 0.6V to 3.4V**
- **Current Mode Constant On-Time (CMCOT) Control**
- **Ultrafast Transient Response**
- **No Needs For External Compensations**
- **Optimized for Low-ESR Ceramic Output Capacitors**
- **0.6 ±2% High-Accuracy Feedback Reference Voltage**
- **LS FETs Protection for Robust Over-Current Protection**
- **Forced PWM Mode**
- **Fixed Switching Frequency : 1.5MHz**
- **Internally Soft-Start Function**
- **Monotonic Start-Up for Pre-Biased Output**
- **Input Under-Voltage Lockout (UVLO)**
- **Output Under-Voltage Protection (UVP) with Hiccup Mode**
- **Enable Control**
- **Available In WDFN-6L 2x2 Package**

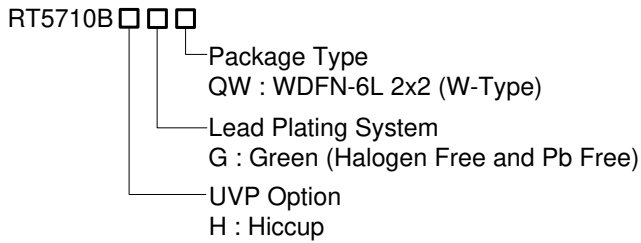
### Applications

- STB, Cable Modem, & xDSL Platforms
- LCD TV Power Supply & Metering Platforms
- General Purpose Point of Load (POL)

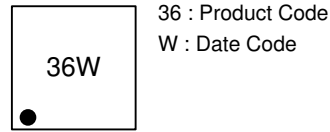
### Simplified Application Circuit



## Ordering Information

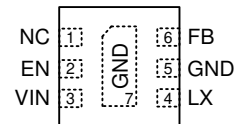


## Marking Information



## Pin Configuration

(TOP VIEW)



WDFN-6L 2x2

Note :

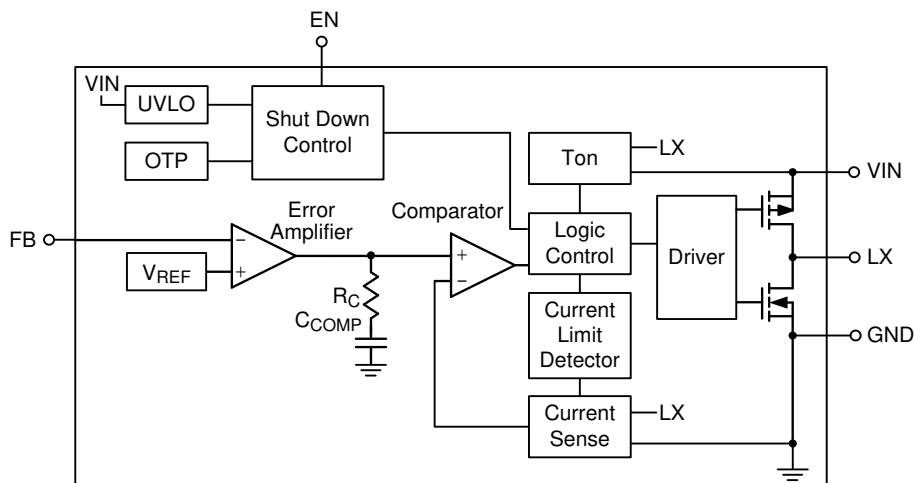
Richtek products are :

- ▶ RoHS compliant and compatible with the current requirements of IPC/JEDEC J-STD-020.
- ▶ Suitable for use in SnPb or Pb-free soldering processes.

## Functional Pin Description

Pin No.	Pin Name	Pin Function
1	NC	No internal connection.
2	EN	Enable control input.
3	VIN	Supply voltage input. The RT5710B operates from a 2.5V to 6V input.
4	LX	Switch node.
5, 7 (Exposed Pad)	GND	Ground. The exposed pad must be soldered to a large PCB and connected to GND for maximum thermal dissipation.
6	FB	Feedback.

## Functional Block Diagram



**Operation**

The RT5710B is a synchronous low voltage step-down converter that can support the input voltage range from 2.5V to 6V and the output current can be up to 1A. The RT5710B uses a constant on-time, current mode architecture. In normal operation, the high-side P-MOSFET is turned on when the switch controller is set by the comparator and is turned off when the Ton comparator resets the switch controller.

Low-side MOSFET peak current is measured by internal RSENSE. The error amplifier EA adjusts COMP voltage by comparing the feedback signal (V<sub>FB</sub>) from the output voltage with the internal 0.6V reference. When the load current increases, it causes a drop in the feedback voltage relative to the reference, then the COMP voltage rises to allow higher inductor current to match the load current.

**UV Comparator**

If the feedback voltage (V<sub>FB</sub>) is lower than threshold voltage 0.2V, the UV comparator's output will go high and the switch controller will turn off the high-side MOSFET. The output under-voltage protection is designed to operate in Hiccup mode.

**Enable Comparator**

A logic-high enables the converter; a logic-low forces the IC into shutdown mode.

**Soft-Start (SS)**

An internal current source charges an internal capacitor to build the soft-start ramp voltage. The V<sub>FB</sub> voltage will track the internal ramp voltage during soft-start interval. The typical soft-start time is 1.2ms.

**Over-Current Protection (OCP)**

The RT5710B provides over-current protection by detecting low-side MOSFET valley inductor current. If the sensed valley inductor current is over the current limit threshold (1.5A typ.), the OCP will be triggered. When OCP is tripped, the RT5710B will keep the over current threshold level until the over current condition is removed.

**Thermal Shutdown (OTP)**

The device implements an internal thermal shutdown function when the junction temperature exceeds 150°C. The thermal shutdown forces the device to stop switching when the junction temperature exceeds the thermal shutdown threshold. Once the die temperature decreases below the hysteresis of 20°C, the device reinstates the power up sequence.

## Absolute Maximum Ratings (Note 1)

• Supply Input Voltage	-----	-0.3V to 6.5V
• LX Pin Switch Voltage	-----	-0.3V to (V <sub>IN</sub> + 0.3V)
<20ns	-----	-4.5V to 7.5V
• Power Dissipation, P <sub>D</sub> @ T <sub>A</sub> = 25°C		
WDFN-6L 2x2	-----	0.833W
• Package Thermal Resistance (Note 2)		
WDFN-6L 2x2, θ <sub>JA</sub>	-----	120°C/W
WDFN-6L 2x2, θ <sub>JC</sub>	-----	7°C/W
• Lead Temperature (Soldering, 10 sec.)	-----	260°C
• Junction Temperature	-----	-40°C to 150°C
• Storage Temperature Range	-----	-65°C to 150°C
• ESD Susceptibility (Note 3)		
HBM (Human Body Model)	-----	2kV

## Recommended Operating Conditions (Note 4)

• Supply Input Voltage	-----	2.5V to 6V
• Ambient Temperature Range	-----	-40°C to 85°C
• Junction Temperature Range	-----	-40°C to 125°C

## Electrical Characteristics

(V<sub>IN</sub> = 3.6V, T<sub>A</sub> = 25°C, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Input Voltage	V <sub>IN</sub>		2.5	--	6	V
Feedback Reference Voltage	V <sub>REF</sub>		0.588	0.6	0.612	V
Feedback Leakage Current	I <sub>FB</sub>	V <sub>FB</sub> = 3.3V	--	--	1	μA
DC Bias Current		Active, V <sub>FB</sub> = 0.63V, not switching	--	300	--	μA
		Shutdown	--	--	1	
Switching Leakage Current			--	--	1	μA
Switching Frequency			--	1.5	--	MHz
Switch On Resistance, High	R <sub>PMOS</sub>	I <sub>SW</sub> = 0.3A	--	160	--	mΩ
Switch On Resistance, Low	R <sub>NMOS</sub>	I <sub>SW</sub> = 0.3A	--	110	--	mΩ
Valley Current Limit	I <sub>LIM</sub>		1.1	1.5	2	A
Under-Voltage Lockout Threshold	V <sub>UVLO</sub>	V <sub>DD</sub> rising	--	2.25	2.5	V
		V <sub>DD</sub> falling	--	2	--	
Over-Temperature Threshold			--	150	--	°C
Enable Input Voltage	Logic-High	V <sub>IH</sub>	1.5	--	--	V
	Logic-Low	V <sub>IL</sub>	--	--	0.4	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Soft-Start Time	t <sub>SS</sub>		--	1.2	--	ms
Minimum Off Time			--	120	--	ns
Output Discharge Switch On Resistance			--	1.8	--	kΩ

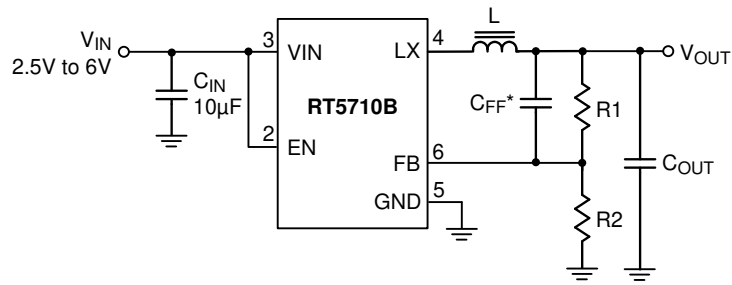
**Note 1.** Stresses beyond those listed “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions may affect device reliability.

**Note 2.**  $\theta_{JA}$  is measured under natural convection (still air) at  $T_A = 25^\circ\text{C}$  with the component mounted on a high effective-thermal-conductivity four-layer test board on a JEDEC 51-7 thermal measurement standard.  $\theta_{JC}$  is measured at the exposed pad of the package.

**Note 3.** Devices are ESD sensitive. Handling precaution recommended.

**Note 4.** The device is not guaranteed to function outside its operating conditions.

## Typical Application Circuit



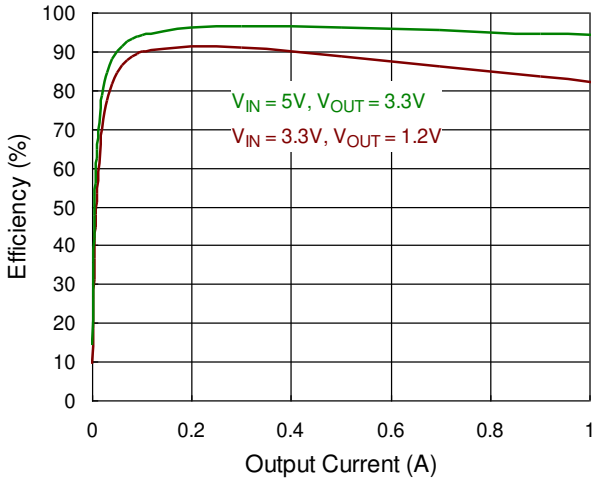
\*CFF : Optional for performance fine-tune

**Table 1. Suggested Component Values**

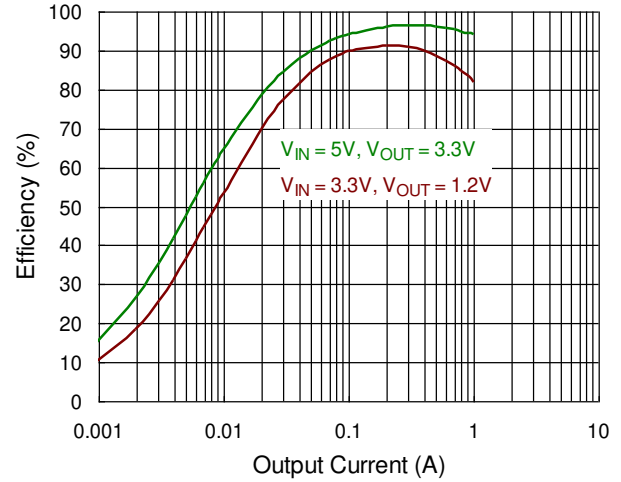
V <sub>OUT</sub> (V)	R1 (kΩ)	R2 (kΩ)	L (μH)	C <sub>OUT</sub> (μF)
3.3	90	20	1.5	10
1.8	100	50	1.5	10
1.5	100	66.6	1.5	10
1.2	100	100	1.5	10
1.05	100	133	1.5	10
1	100	148	1.5	10

**Typical Operating Characteristics**

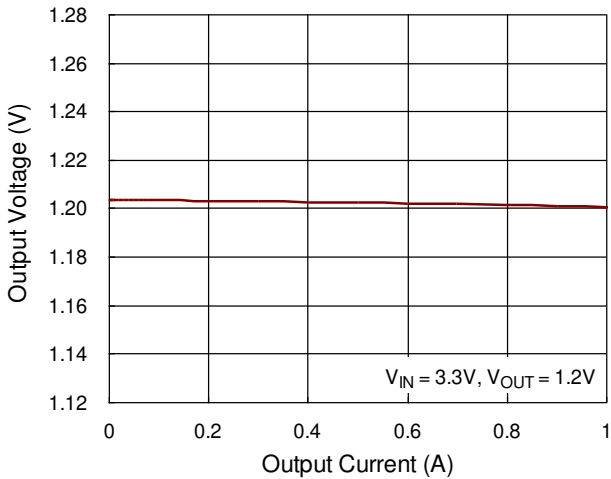
**Efficiency vs. Output Current**



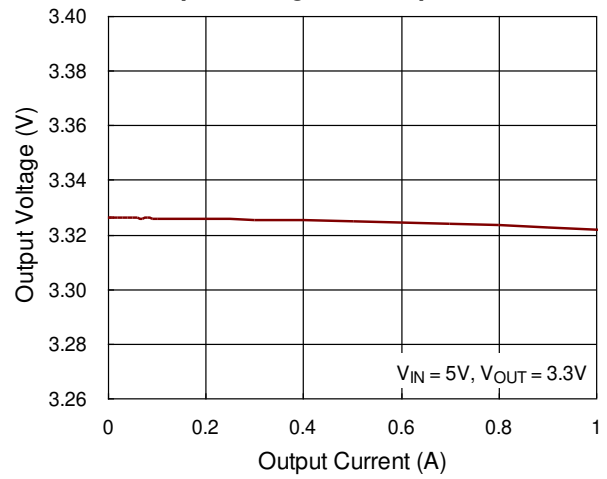
**Efficiency vs. Output Current**



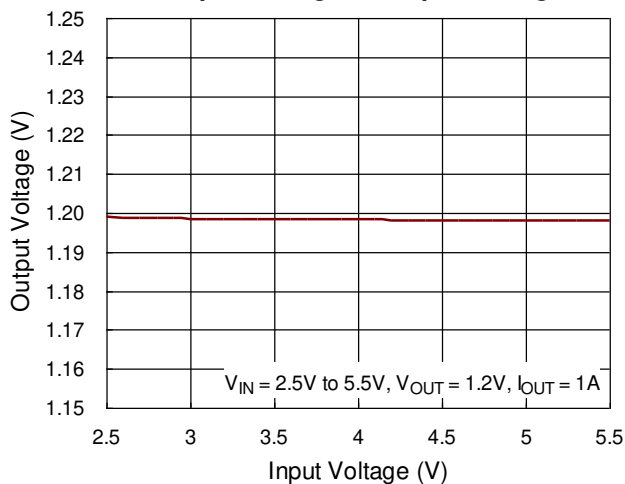
**Output Voltage vs. Output Current**



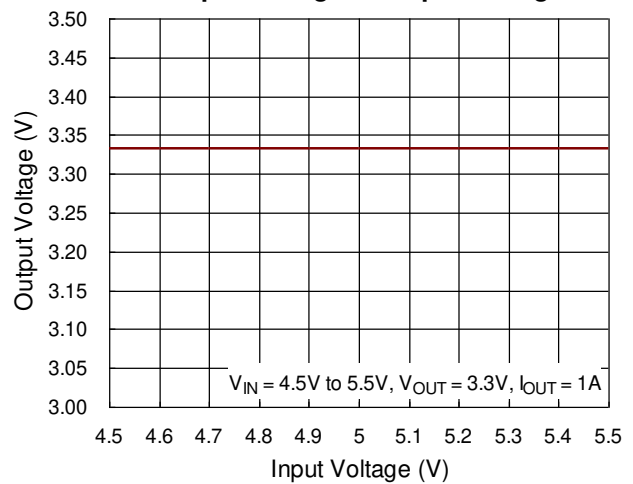
**Output Voltage vs. Output Current**



**Output Voltage vs. Input Voltage**

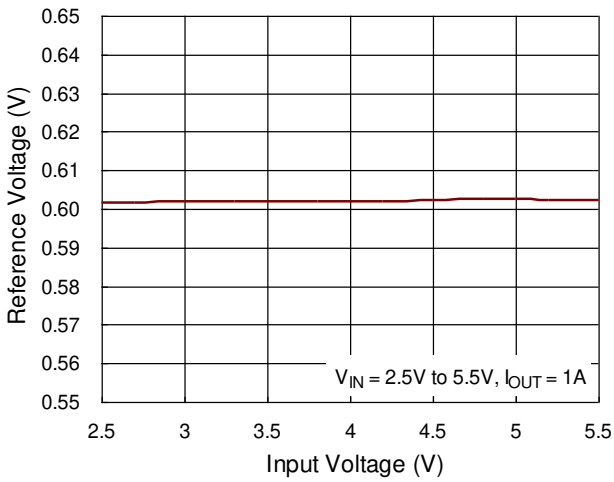


**Output Voltage vs. Input Voltage**

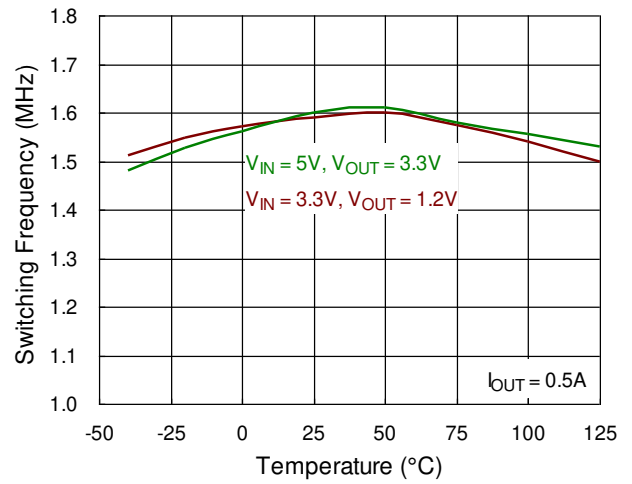




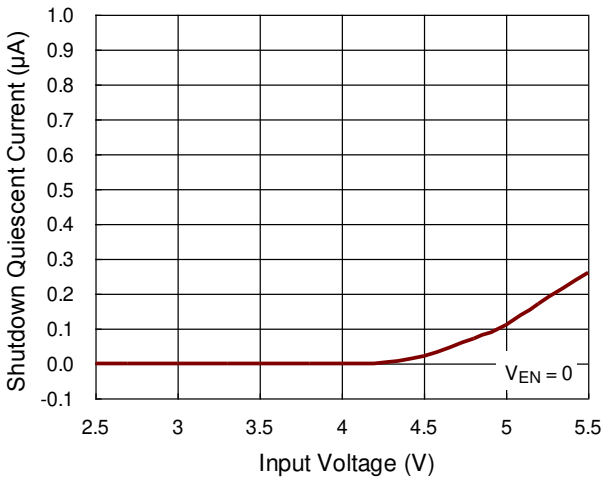
Reference Voltage vs. Input Voltage



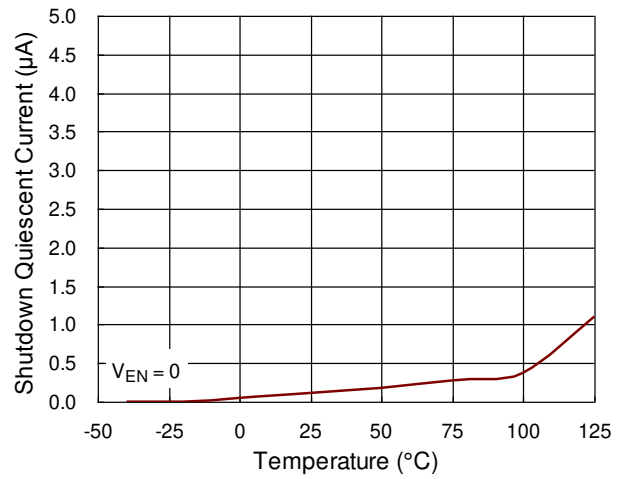
Switching Frequency vs. Temperature



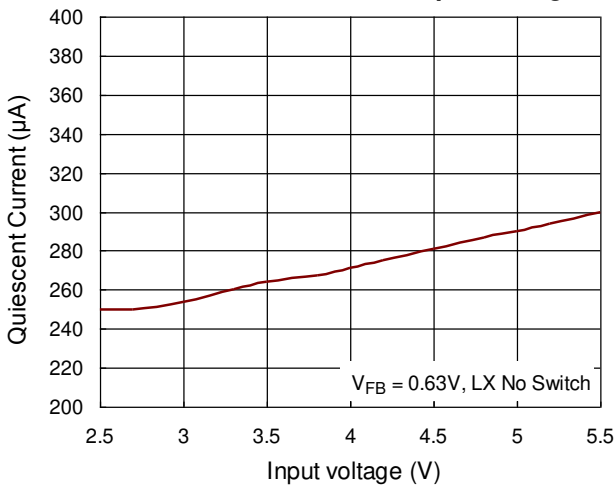
Shutdown Quiescent Current vs. Input Voltage



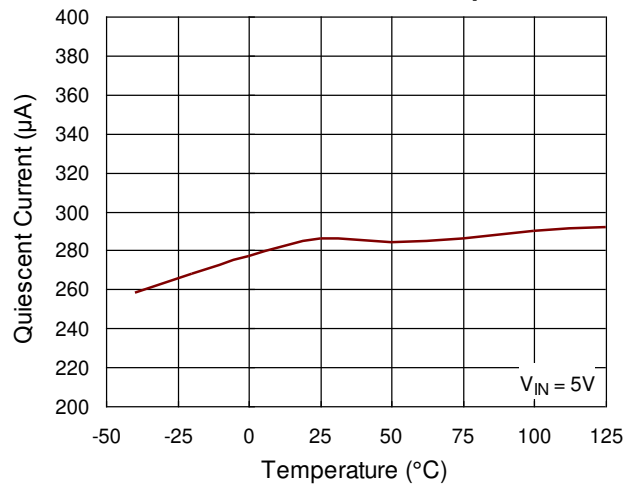
Shutdown Quiescent Current vs. Temperature



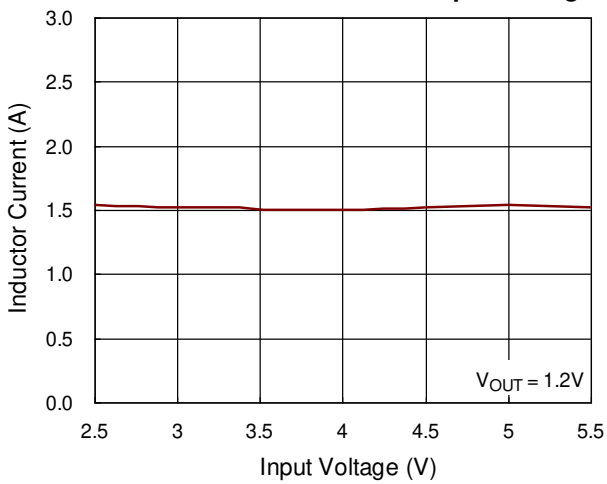
Quiescent Current vs. Input Voltage



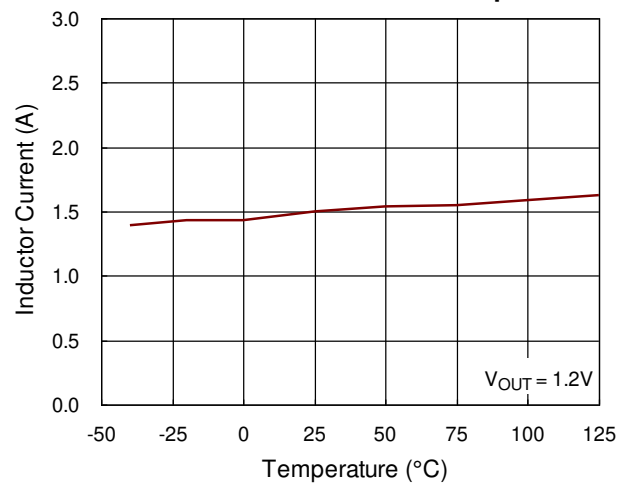
Quiescent Current vs. Temperature



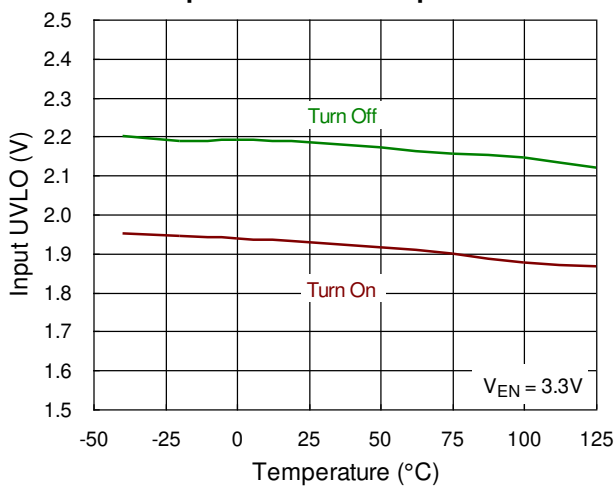
**Inductor Current Limit vs. Input Voltage**



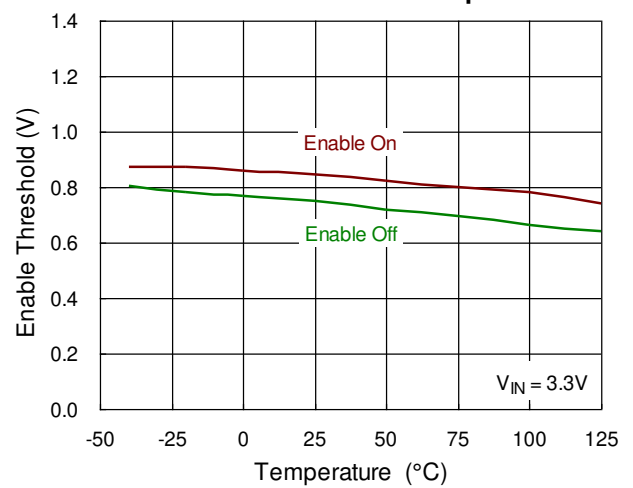
**Inductor Current Limit vs. Temperature**



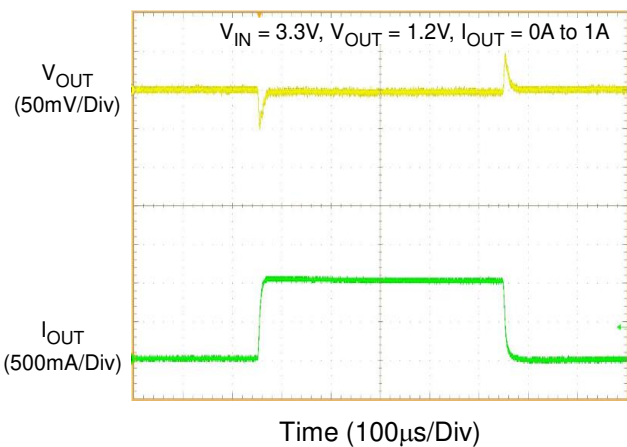
**Input UVLO vs. Temperature**



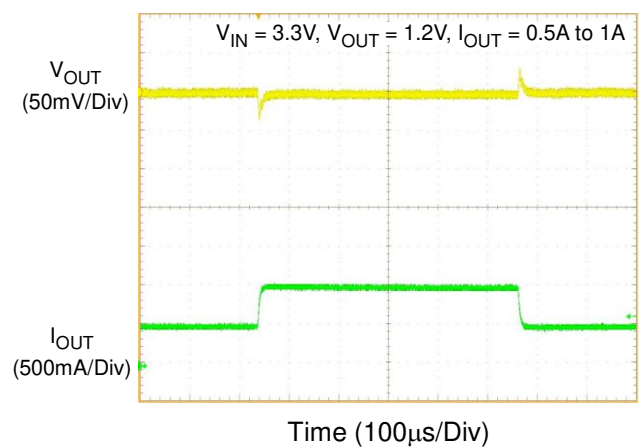
**Enable Threshold vs. Temperature**



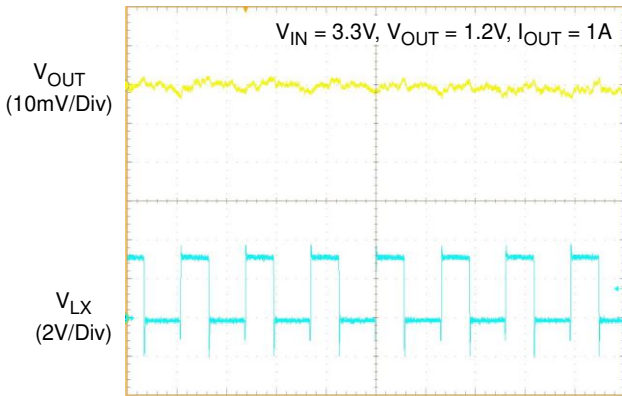
**Load Transient Response**



**Load Transient Response**

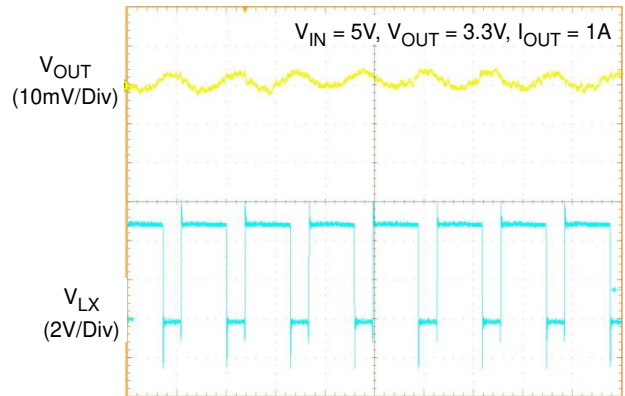


Voltage Ripple



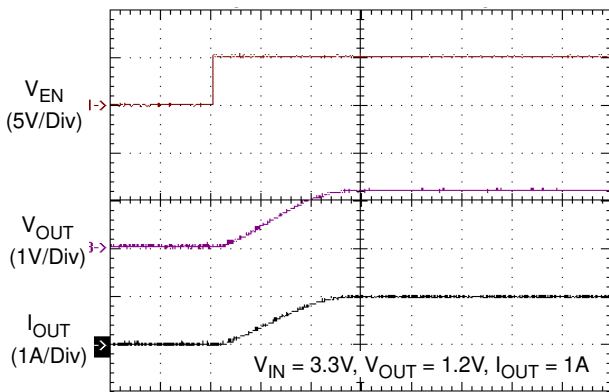
Time (500ns/Div)

Voltage Ripple



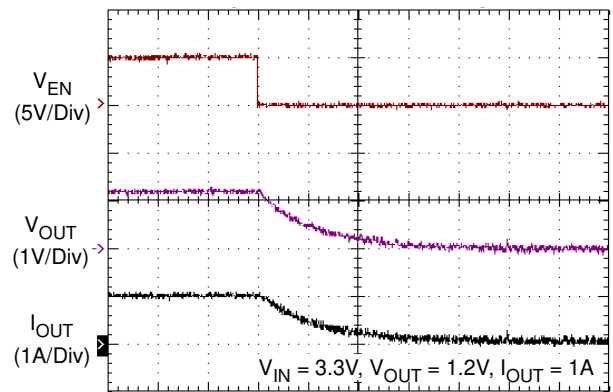
Time (500ns/Div)

Power On from EN



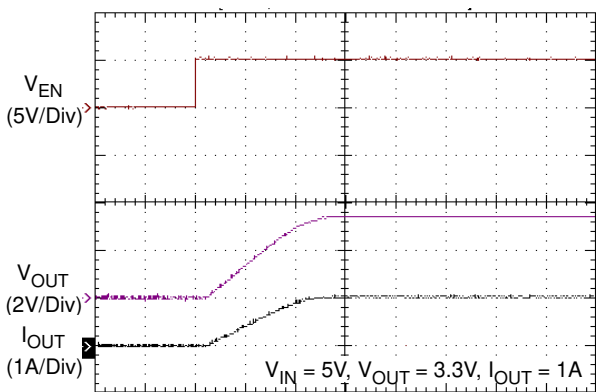
Time (500 $\mu$ s/Div)

Power Off from EN



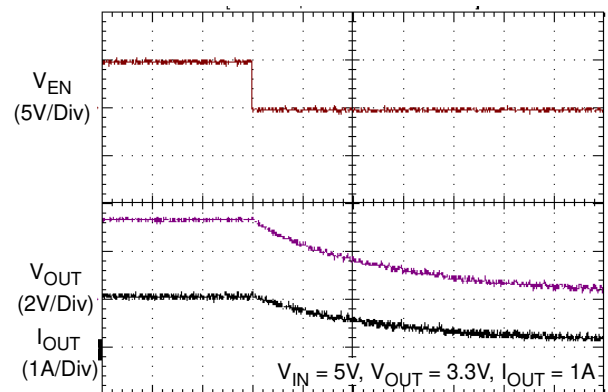
Time (10 $\mu$ s/Div)

Power On from EN



Time (500 $\mu$ s/Div)

Power Off from EN



Time (10 $\mu$ s/Div)

**Application Information**

The RT5710B is a single-phase step-down converter. It provides single feedback loop, constant on-time current mode control with fast transient response. An internal 0.6V reference allows the output voltage to be precisely regulated for low output voltage applications. A fixed switching frequency (1.5MHz) oscillator and internal compensation are integrated to minimize external component count. Protection features include over-current protection, under-voltage protection and over-temperature protection.

**Output Voltage Setting**

Connect a resistive voltage divider at the FB between V<sub>OUT</sub> and GND to adjust the output voltage. The output voltage is set according to the following equation :

$$V_{OUT} = V_{REF} \times \left(1 + \frac{R1}{R2}\right)$$

where V<sub>REF</sub> is the feedback reference voltage 0.6V (typ.).

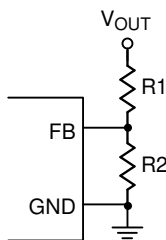


Figure 1. Setting V<sub>OUT</sub> with a Voltage Divider

**Chip Enable and Disable**

The EN pin allows for power sequencing between the controller bias voltage and another voltage rail. The RT5710B remains in shutdown if the EN pin is lower than 400mV. When the EN pin rises above the V<sub>EN</sub> trip point, the RT5710B begins a new initialization and soft-start cycle.

**Internal Soft-Start**

The RT5710B provides an internal soft-start function to prevent large inrush current and output voltage overshoot when the converter starts up. The soft-start (SS) automatically begins once the chip is enabled. During soft-start, the internal soft-start capacitor becomes charged and generates a linear ramping up voltage across the capacitor. This voltage clamps the

voltage at the FB pin, causing PWM pulse width to increase slowly and in turn reduce the input surge current. The internal 0.6V reference takes over the loop control once the internal ramping-up voltage becomes higher than 0.6V.

**UVLO Protection**

The RT5710B has input Under Voltage Lockout protection (UVLO). If the input voltage exceeds the UVLO rising threshold voltage (2.25V typ.), the converter resets and prepares the PWM for operation. If the input voltage falls below the UVLO falling threshold voltage during normal operation, the device will stop switching. The UVLO rising and falling threshold voltage has a hysteresis to prevent noise-caused reset.

**Inductor Selection**

The switching frequency (on-time) and operating point (% ripple or LIR) determine the inductor value as shown below :

$$L = \frac{V_{OUT} \times (V_{IN} - V_{OUT})}{f_{SW} \times LIR \times I_{LOAD(MAX)} \times V_{IN}}$$

where LIR is the ratio of the peak-to-peak ripple current to the average inductor current.

Find a low loss inductor having the lowest possible DC resistance that fits in the allotted dimensions. The core must be large enough not to saturate at the peak inductor current (I<sub>PEAK</sub>) :

$$I_{PEAK} = I_{LOAD(MAX)} + \left(\frac{LIR}{2} \times I_{LOAD(MAX)}\right)$$

The calculation above serves as a general reference. To further improve transient response, the output inductor can be further reduced. This relation should be considered along with the selection of the output capacitor.

Inductor saturation current should be chosen over IC's current limit.

**Input Capacitor Selection**

High quality ceramic input decoupling capacitor, such as X5R or X7R, with values greater than 10μF are recommended for the input capacitor. The X5R and

X7R ceramic capacitors are usually selected for power regulator capacitors because the dielectric material has less capacitance variation and more temperature stability.

Voltage rating and current rating are the key parameters when selecting an input capacitor. Generally, selecting an input capacitor with voltage rating 1.5 times greater than the maximum input voltage is a conservatively safe design.

The input capacitor is used to supply the input RMS current, which can be approximately calculated using the following equation :

$$I_{IN\_RMS} = I_{LOAD} \times \sqrt{\frac{V_{OUT}}{V_{IN}} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right)}$$

The next step is selecting a proper capacitor for RMS current rating. One good design uses more than one capacitor with low equivalent series resistance (ESR) in parallel to form a capacitor bank.

The input capacitance value determines the input ripple voltage of the regulator. The input voltage ripple can be approximately calculated using the following equation :

$$\Delta V_{IN} = \frac{I_{OUT(MAX)}}{C_{IN} \times f_{SW}} \times \frac{V_{OUT}}{V_{IN}} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right)$$

### Output Capacitor Selection

The output capacitor and the inductor form a low pass filter in the Buck topology. In steady state condition, the ripple current flowing into/out of the capacitor results in ripple voltage. The output voltage ripple ( $V_{P-P}$ ) can be calculated by the following equation :

$$V_{P-P} = LIR \times I_{LOAD(MAX)} \times \left(ESR + \frac{1}{8 \times C_{OUT} \times f_{SW}}\right)$$

When load transient occurs, the output capacitor supplies the load current before the controller can respond. Therefore, the ESR will dominate the output voltage sag during load transient. The output voltage undershoot ( $V_{SAG}$ ) can be calculated by the following equation :

$$V_{SAG} = \Delta I_{LOAD} \times ESR$$

For a given output voltage sag specification, the ESR value can be determined.

Another parameter that has influence on the output voltage sag is the equivalent series inductance (ESL). The rapid change in load current results in di/dt during transient. Therefore, the ESL contributes to part of the voltage sag. Using a capacitor with low ESL can obtain better transient performance. Generally, using several capacitors connected in parallel can have better transient performance than using a single capacitor for the same total ESR.

### Thermal Considerations

The junction temperature should never exceed the absolute maximum junction temperature  $T_{J(MAX)}$ , listed under Absolute Maximum Ratings, to avoid permanent damage to the device. The maximum allowable power dissipation depends on the thermal resistance of the IC package, the PCB layout, the rate of surrounding airflow, and the difference between the junction and ambient temperatures. The maximum power dissipation can be calculated using the following formula :

$$P_{D(MAX)} = (T_{J(MAX)} - T_A) / \theta_{JA}$$

where  $T_{J(MAX)}$  is the maximum junction temperature,  $T_A$  is the ambient temperature, and  $\theta_{JA}$  is the junction-to-ambient thermal resistance.

For continuous operation, the maximum operating junction temperature indicated under Recommended Operating Conditions is 125°C. The junction-to-ambient thermal resistance,  $\theta_{JA}$ , is highly package dependent. For WDFN-6L 2x2 package, the thermal resistance,  $\theta_{JA}$ , is 120°C/W on a standard JEDEC 51-7 high effective-thermal-conductivity four-layer test board. The maximum power dissipation at  $T_A = 25^\circ\text{C}$  can be calculated as below :

$$P_{D(MAX)} = (125^\circ\text{C} - 25^\circ\text{C}) / (120^\circ\text{C/W}) = 0.833\text{W for a WDFN-6L 2x2 package.}$$

The maximum power dissipation depends on the operating ambient temperature for the fixed  $T_{J(MAX)}$  and the thermal resistance,  $\theta_{JA}$ . The derating curve in Figure 2 allows the designer to see the effect of rising ambient temperature on the maximum power dissipation.

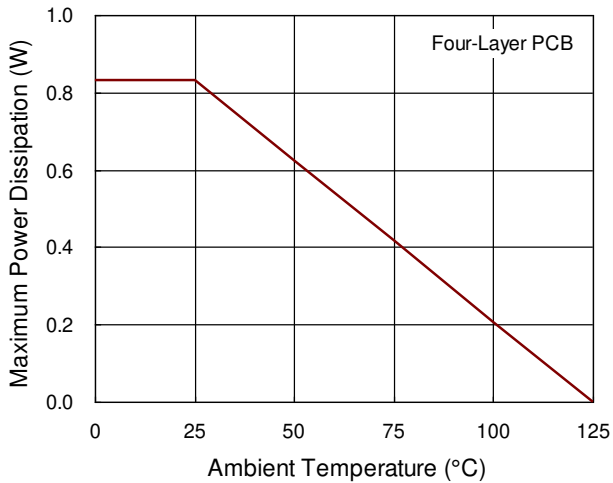


Figure 2. Derating Curve of Maximum Power Dissipation

**Layout Considerations**

For best performance of the RT5710B, the following layout guidelines must be strictly followed.

- ▶ Input capacitor must be placed as close to the IC as possible.
- ▶ LX should be connected to inductor by wide and short trace. Keep sensitive components away from this trace.
- ▶ Keep every trace connected to pin as wide as possible for improving thermal dissipation.
- ▶ The feedback components must be connected as close to the device as possible.
- ▶ Via can help to reduce power trace and improve thermal dissipation.

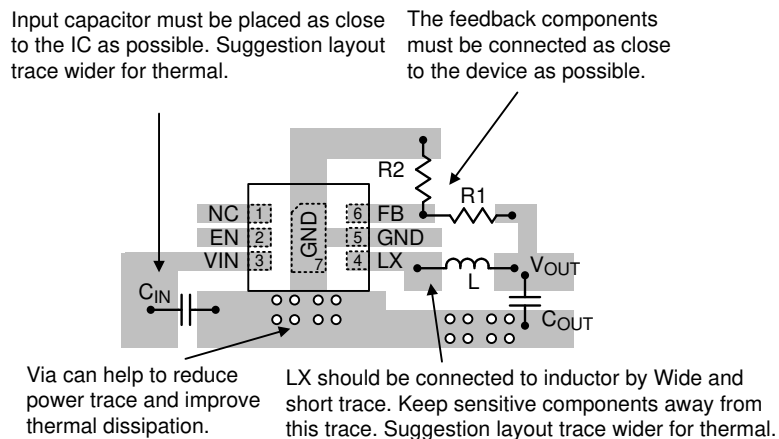
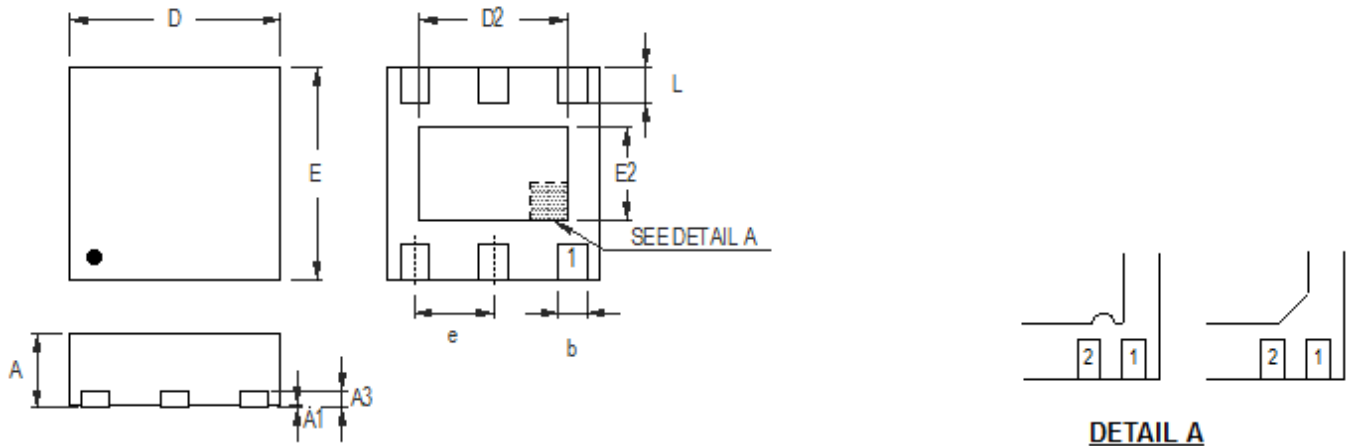


Figure 3. PCB Layout Guide

Outline Dimension



DETAIL A  
Pin #1 ID and Tie Bar Mark Options

Note : The configuration of the Pin #1 identifier is optional, but must be located within the zone indicated.

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A3	0.175	0.250	0.007	0.010
b	0.200	0.350	0.008	0.014
D	1.950	2.050	0.077	0.081
D2	1.000	1.450	0.039	0.057
E	1.950	2.050	0.077	0.081
E2	0.500	0.850	0.020	0.033
e	0.650		0.026	
L	0.300	0.400	0.012	0.016

W-Type 6L DFN 2x2 Package

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